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54AC241 • 54ACT241 Octal Buffer/Line Driver with Outputs

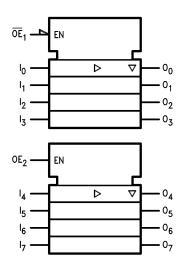
Check for Samples: 54AC241, 54ACT241-N

FEATURES

- I_{CC} and I_{OZ} Reduced by 50%
- Non-Inverting TRI-STATE Outputs Drive Bus Lines or Buffer Memory Address Registers
- Outputs Source/Sink 24 mA
- 'ACT241 has TTL-Compatible Inputs
- Standard Microcircuit Drawing (SMD)

'AC241: 5962-87551'ACT241: 5962-89847

Logic Symbol



DESCRIPTION

The 'AC/'ACT241 is an octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus-oriented transmitter or receiver which provides improved PC board density.

Pin Names	Description
\overline{OE}_1 ,	TRI-STATE Output Enable Input
OE ₂	TRI-STATE Output Enable Input (Active HIGH)
I ₀ -I ₇	Inputs
O ₀ -O ₇	Outputs

Connection Diagrams

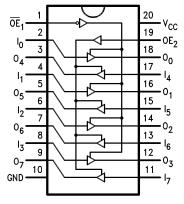


Figure 1. 20-Pin CERDIP or CLGA See NAF0020A Package

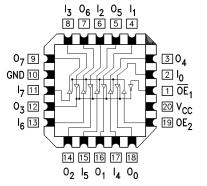


Figure 2. 20-Pin LCCC See NAJ0020A Package



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TRUTH TABLE(1)

Inputs		Outputs
ŌE ₁	l _n	(Pins 12, 14, 16, 18)
L	L	L
L	Н	Н
Н	X	Z
Inpu	uts	Outputs
Inpu OE ₂	uts I _n	Outputs (Pins 3, 5, 7, 9)
-		·
OE ₂		·

(1) H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS(1)(2)

Supply Voltage (V _{CC})		-0.5V to +7.0V
DC Input Diode Current (I _{IK})	V₁ = −0.5V	−20 mA
	$V_I = V_{CC} + 0.5V$	+20 mA
DC Input Voltage (V _I)		-0.5V to V _{CC} + 0.5 V
DC Output Diode Current (I _{OK})	V _O = −0.5V	−20 mA
	$V_O = V_{CC} + 0.5V$	+20 mA
DC Output Voltage (V _O)		-0.5V to V _{CC} + 0.5 V
DC Output Source or Sink Current (I _O)		±50 mA
DC V _{CC} or Ground Current per Output Pin (I _{CC} or I _{GND})		±50 mA
Storage Temperature (T _{STG})		-65°C to +150°C
Junction Temperature (T _J) CERDIP		175°C

- (1) Absolute Maximum Ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. Texas Instruments does not recommend operation of FACT circuits outside databook specifications.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

RECOMMENDED OPERATING CONDITIONS

Supply Voltage (V _{CC})		'AC	2.0V to 6.0V
		'ACT	4.5V to 5.5V
Input Voltage (V _I)		1.72	0V to V _{CC}
Output Voltage (V _O)			0V to V _{CC}
Operating Temperature (T _A)		54AC/ACT	−55°C to +125°C
Minimum Input Edge Rate (ΔV/Δt) 'AC Devices		V _{IN} from 30% to 70% of V _{CC}	
		V _{CC} @ 3.3V, 4.5V, 5.5V	125 mV/ns
Minimum Input Edge Rate (ΔV/Δt)	'ACT Devices	V _{IN} from 0.8V to 2.0V	
		V _{CC} @ 4.5V, 5.5V	125 mV/ns

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DC CHARACTERISTICS FOR 'AC FAMILY DEVICES

			54AC		
Symbol	Parameter	V _{CC}	T _A =	Units	Conditions
-		(V)	-55°C to +125°C		
			Specified Limits		
V _{IH}	Minimum High Level	3.0	2.1		V _{OUT} = 0.1V
	Input Voltage	4.5	3.15	V	or V _{CC} - 0.1V
		5.5	3.85		
V _{IL}	Maximum Low Level	3.0	0.9		V _{OUT} = 0.1V
	Input Voltage	4.5	1.35	V	or V _{CC} - 0.1V
		5.5	1.65		
V _{OH}	Minimum High Level	3.0	2.9		I _{OUT} = -50 μA
	Output Voltage	4.5	4.4	V	
		5.5	5.4		
					See ⁽¹⁾ V _{IN} = V _{IL} or V _{IH}
		3.0	2.4		I _{OH} = −12 mA
		4.5	3.7	V	I _{OH} = −24 mA
		5.5	4.7		I _{OH} = −24 mA
V _{OL}	Maximum Low Level	3.0	0.1		I _{OUT} = 50 μA
	Output Voltage	4.5	0.1	V	
		5.5	0.1		
					See ⁽¹⁾ V _{IN} = V _{IL} or V _{IH}
		3.0	0.50		$I_{OL} = 12 \text{ mA}$
		4.5	0.50	V	$I_{OL} = 24 \text{ mA}$
		5.5	0.50		$I_{OL} = 24 \text{ mA}$
I _{IN}	Maximum Input	5.5	±1.0	μA	$V_I = V_{CC}$, GND
	Leakage Current				
l _{OZ}	Maximum TRI-STATE				V_{I} (OE) = V_{IL} , V_{IH}
	Leakage Current	5.5	±5.0	μA	$V_I = V_{CC}$, GND
					$V_O = V_{CC}$, GND
I _{OLD}	Minimum Dynamic	5.5	50	mA	V _{OLD} = 1.65V Max
I _{OHD}	Output Current ⁽²⁾	5.5	- 50	mA	V _{OHD} = 3.85V Min
I _{CC}	Maximum Quiescent	5.5	80.0	μA	$V_{IN} = V_{CC}$
	Supply Current				or GND

⁽¹⁾ All outputs loaded; thresholds on input associated with output under test.

⁽²⁾ Maximum test duration 2.0 ms, one output loaded at a time.



DC CHARACTERISTICS FOR 'ACT FAMILY DEVICES

			54ACT		Conditions
Symbol	Parameter	V _{CC}	T _A =	Units	
		(V)	-55°C to +125°C		
			Specified Limits		
V _{IH}	Minimum High Level	4.5	2.0	V	V _{OUT} = 0.1V
	Input Voltage	5.5	2.0		or V _{CC} - 0.1V
V _{IL}	Maximum Low Level	4.5	0.8	V	$V_{OUT} = 0.1V$
	Input Voltage	5.5	0.8		or V _{CC} - 0.1V
V _{OH}	Minimum High Level	4.5	4.4	V	I _{OUT} = -50 μA
	Output Voltage	5.5	5.4		
					$See^{(1)}$ $V_{IN} = V_{IL} \text{ or } V_{IH}$
		4.5	3.70	V	I _{OH} = −24 mA
		5.5	4.70		I _{OH} = −24 mA
V _{OL}	Maximum Low Level	4.5	0.1	V	I _{OUT} = 50 μA
	Output Voltage	5.5	0.1		
					$See^{(1)}$ $V_{IN} = V_{IL} \text{ or } V_{IH}$
		4.5	0.50	V	$I_{OL} = 24 \text{ mA}$
		5.5	0.50		$I_{OL} = 24 \text{ mA}$
I _{IN}	Maximum Input Leakage Current	5.5	±1.0	μA	$V_I = V_{CC}$, GND
l _{oz}	Maximum TRI-STATE	5.5	±5.0	μA	$V_{I} = V_{IL}, V_{IH}$
	Leakage Current				$V_O = V_{CC}$, GND
I _{CCT}	Maximum	5.5	1.6	mA	$V_1 = V_{CC} - 2.1V$
	I _{CC} /Input				
I _{OLD}	Minimum Dynamic	5.5	50	mA	V _{OLD} = 1.65V Max
I _{OHD}	Output Current ⁽²⁾	5.5	-50	mA	V _{OHD} = 3.85V Min
I _{CC}	Maximum Quiescent	5.5	80.0	μA	$V_{IN} = V_{CC}$
	Supply Current				or GND

⁽¹⁾ All outputs loaded; thresholds on input associated with output under test.

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⁽²⁾ Maximum test duration 2.0 ms, one output loaded at a time.

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AC ELECTRICAL CHARACTERISTICS

See for waveforms

			54AC T _A = -55°C			Fig. No.
		V _{CC}				
Symbol	Parameter	(V) ⁽¹⁾	to +	to +125°C C _L = 50 pF		
			C _L =			
			Min	Max		
t _{PLH}	Propagation Delay	3.3	1.0	12.0	ns	
	Data to Output	5.0	1.0	9.5		
t _{PHL}	Propagation Delay	3.3	1.0	11.5	ns	
	Data to Output	5.0	1.0	9.0		
t _{PZH}	Output Enable Time	3.3	1.0	13.0	ns	
		5.0	1.0	10.0		
t _{PZL}	Output Enable Time	3.3	1.0	13.0	ns	
		5.0	1.0	10.0		
t _{PHZ}	Output Disable Time	3.3	1.0	13.0	ns	
		5.0	1.0	11.5		
t _{PLZ}	Output Disable Time	3.3	1.0	13.0	ns	
		5.0	1.0	11.5		

⁽¹⁾ Voltage Range 3.3 is 3.3V ± 3.3 V Voltage Range 5.0 is 5.0V ± 0.5 V.

AC ELECTRICAL CHARACTERISTICS

See for waveforms

	Parameter		54ACT T _A = -55°C to +125°C C _L = 50 pF		Units	
Symbol		V _{CC} (V) See ⁽¹⁾				Fig. No.
			Min	Max		
t _{PLH}	Propagation Delay	5.0	1.0	10.0	ns	
	Data to Output					
t _{PHL}	Propagation Delay	5.0	1.0	10.0	ns	
	Data to Output					
t _{PZH}	Output Enable Time	5.0	1.0	11.5	ns	
t _{PZL}	Output Enable Time	5.0	1.0	12.5	ns	
t _{PHZ}	Output Disable Time	5.0	1.0	12.5	ns	
t _{PLZ}	Output Disable Time	5.0	1.0	12.5	ns	

⁽¹⁾ Voltage Range 5.0 is 5.0V \pm 0.5V.

CAPACITANCE

Symbol	Parameter	Тур	Units	Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = OPEN
C_{PD}	Power Dissipation Capacitance	45.0	pF	V _{CC} = 5.0V

Product Folder Links: 54AC241 54ACT241-N



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REVISION HISTORY

Changes from Revision A (April 2013) to Revision B			је
•	Changed layout of National Data Sheet to TI format		5

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